

1A SURFACE MOUNT SCHOTTKY BRIDGE

FEATURES:

- Reverse Voltage - 40 to 200 V
- Forward Current - 1 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



MBF Package

MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0024oz

Maximum Ratings and Electrical characteristics

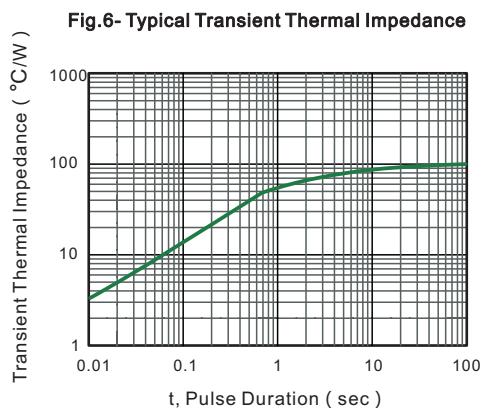
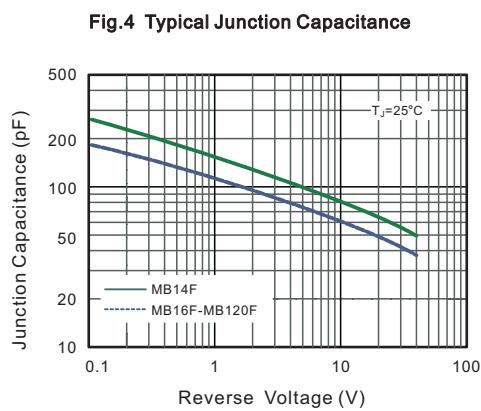
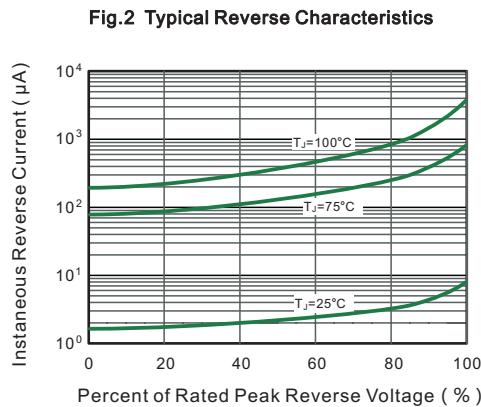
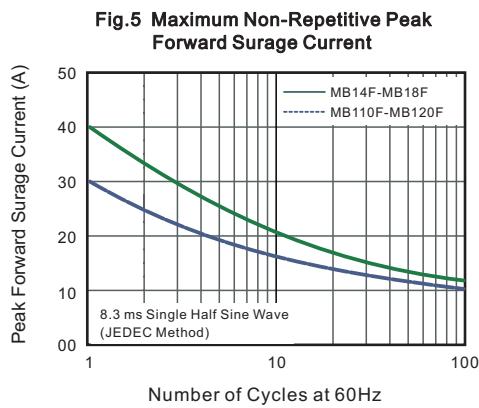
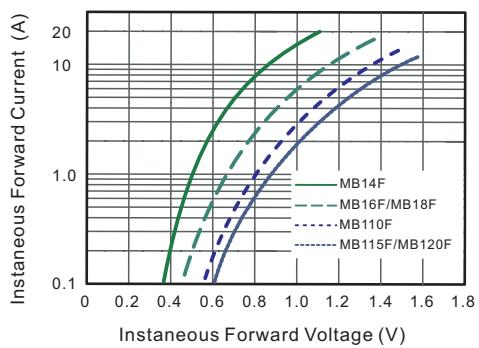
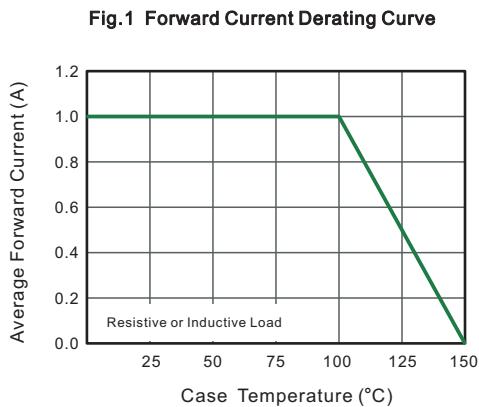
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB14F	MB16F	MB18F	MB110F	MB115F	MB120F	Units					
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	40	60	80	100	150	200	V					
Maximum RMS voltage	V _{RMS}	28	42	56	70	105	140	V					
Maximum DC Blocking Voltage	V _{DC}	40	60	80	100	150	200	V					
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0						A					
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	40			30			A					
Max Instantaneous Forward Voltage at 1 A	V _F	0.55	0.70	0.85	0.90			V					
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a = 100°C	I _R	0.3 10		0.2 5	0.1 2			mA					
Typical Junction Capacitance ¹⁾	C _j	110	80					pF					
Typical Thermal Resistance ²⁾	R _{θJA}	100						°C/W					
Operating Junction Temperature Range	T _j	-55 ~ +150						°C					
Storage Temperature Range	T _{stg}	-55 ~ +150						°C					

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

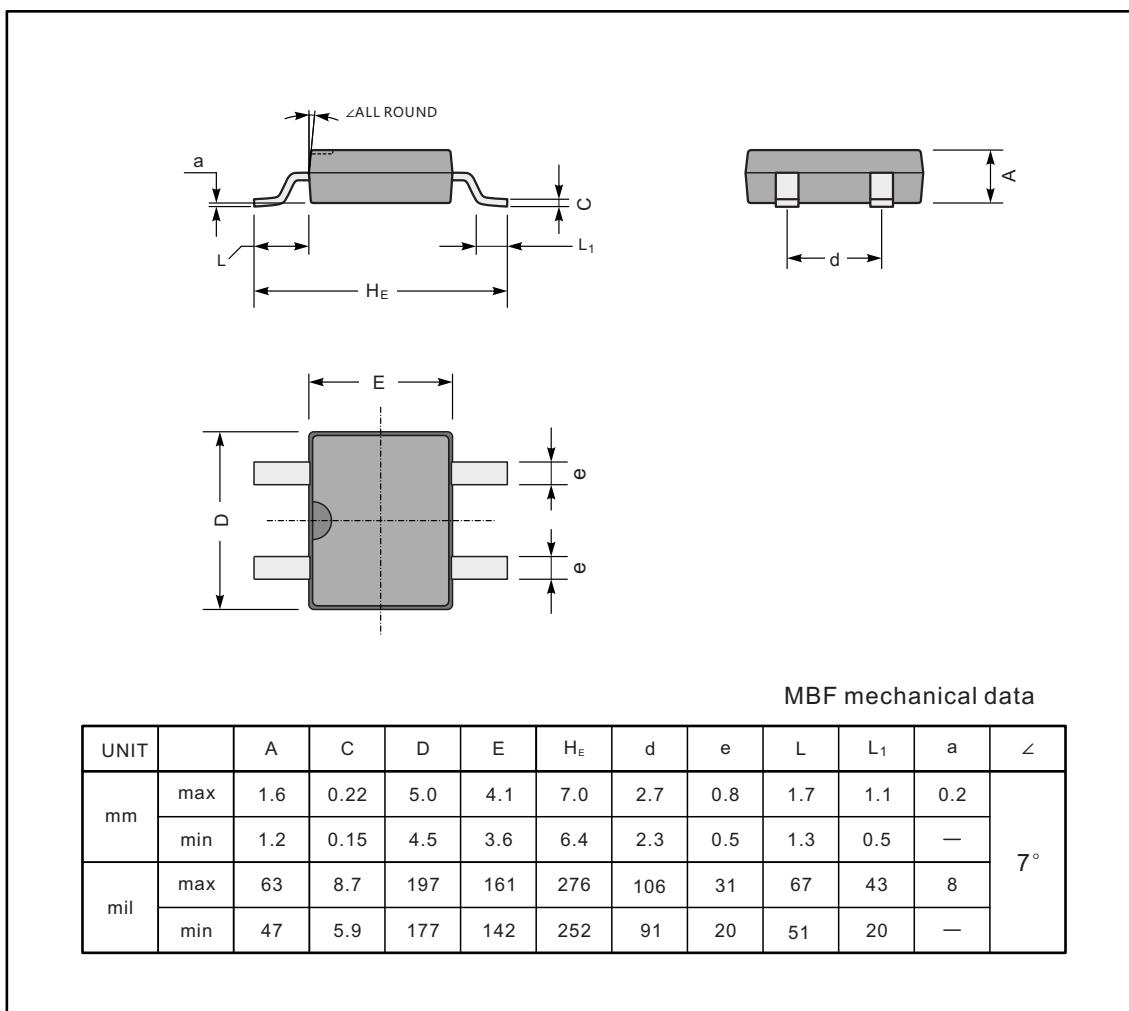
2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.



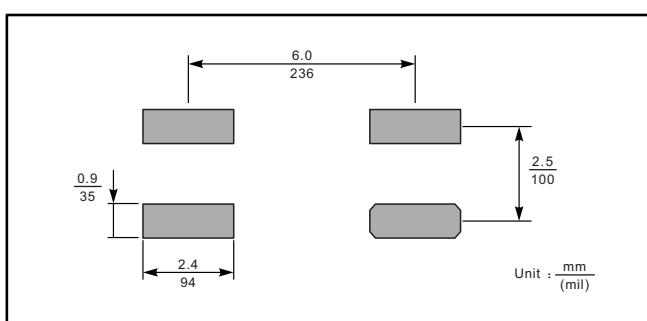
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBF



The recommended mounting pad size



Marking

Type number	Marking code
MB14F	MB14F
MB16F	MB16F
MB18F	MB18F
MB110F	MB110F
MB115F	MB115F
MB120F	MB120F

